



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov



CONFIRMATION NO. 7930

Bib Data Sheet

SERIAL NUMBER 10/018,188	FILING DATE 12/18/2001 RULE	CLASS 451	GROUP ART UNIT 3723	ATTORNEY DOCKET NO. 511.40998X00
-----------------------------	-----------------------------------	--------------	------------------------	--

APPLICANTS

Naoyuki Koyama, Ibaraki, JAPAN;
Kouji Haga, Ibaraki, JAPAN;
Masato Yoshida, Ibaraki, JAPAN;
Keizou Hirai, Ibaraki, JAPAN;
Toronosuke Ashizawa, Ibaraki, JAPAN;
Youiti Machii, Ibaraki, JAPAN;

** CONTINUING DATA *****

THIS APPLICATION IS A 371 OF PCT/JP00/03891 06/15/2000

** FOREIGN APPLICATIONS *****

JAPAN 172821/1999 06/18/1999
JAPAN 204842/1999 07/19/1999
JAPAN 332221/1999 11/24/1999

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY	SHEETS DRAWING	TOTAL CLAIMS	INDEPENDENT CLAIMS
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	JAPAN		12	2
Verified and Acknowledged	<i>[Signature]</i> Examiner's Signature <i>[Initials]</i>				

ADDRESS

Antonelli Terry Stout & Kraus
Suite 1800
1300 North Seventeenth Street
Arlington ,VA 22209

TITLE

Abrasive compound for cmp, method for polishing substrate and method for manufacturing semiconductor device using the same, and additive for cmp abrasive compound

FILING FEE RECEIVED 890	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
		<input type="checkbox"/> 1.16 Fees (Filing)
		<input type="checkbox"/> 1.17 Fees (Processing Ext. of time)
		<input type="checkbox"/> 1.18 Fees (Issue)
		<input type="checkbox"/> Other _____
		<input type="checkbox"/> Credit